



Material Content Data Sheet



Sales Product Name		SAK-TC1766-192F80HL BD		Issued		20. November 2015		
MA#		MA000928068						
Package		PG-LQFP-176-14		Weight*		2045.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	36.463	1.78	1.78	17827	17827
leadframe	non noble metal	magnesium	7439-95-4	0.746	0.04		365	
	inorganic material	silicon	7440-21-3	3.234	0.16		1581	
	non noble metal	nickel	7440-02-0	14.926	0.73		7297	
wire	non noble metal	copper	7440-50-8	478.622	23.40	24.33	234000	243243
	noble metal	gold	7440-57-5	3.526	0.17	0.17	1724	1724
	encapsulation	organic material	carbon black	1333-86-4	4.452	0.22		2177
plastics		epoxy resin	-	136.527	6.67		66748	
	inorganic material	silicondioxide	60676-86-0	1343.008	65.66	72.55	656601	725526
leadfinish	non noble metal	tin	7440-31-5	15.333	0.75	0.75	7496	7496
plating	noble metal	silver	7440-22-4	2.988	0.15	0.15	1461	1461
glue	plastics	epoxy resin	-	1.393	0.07		681	
	noble metal	silver	7440-22-4	4.178	0.20	0.27	2042	2723
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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